

**Amendments to the Specification:**

Please change the Title of the Invention as follows:

PHOTOMASK ASSEMBLY INCORPORATING A POROUS FRAME AND  
~~METHOD FOR MAKING IT~~

Please replace paragraph [0039] with the following amended paragraph:

**[0039]** The CTE of the porous frame should closely match that of the photomask substrate and/or that of an overlying hard pellicle, to minimize distortion of the pattern on the photomask substrate and the pellicle caused by heating of the assembly during the manufacturing of electronic chips. The CTE of the frame preferably is in the range of 0.01 ppm/°C to 10 ppm/°C, more preferably is in the range of 0.1 ppm/°C to 1 ppm/°C, and most preferably is in the range of 0.3 ppm/°C to 0.7 ppm/°C. The most preferable material for the porous frame is a material having a CTE value that closely matches that of the photomask substrate and/or the hard pellicle, ~~with~~ within a difference of  $\pm 20\%$ .